

## LINEAR TECHNOLOGY MATERIALS DECLARATION

LTC1606IG#TRPBF

(Engineering Calculation)

SSOP

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TOTAL MASS (g): 0.234396

COMPONENT MATERIAL	VENDOR/INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL Pkg.	
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.000943	1000000	2534.5351562	
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0	
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.123431	975000	52225.625	
		Iron (Fe)	7439-89-6	0.003014	24000	1288.5849609	
		Phosphorus (P)	7723-14-0	0.000038	300	162.118835449	
		Zinc (Zn)	7440-66-6	0.000088	700	375.431135986	
		Nickel (Ni)	7440-02-0	0.000000	0	0	
		Silicon (Si)	7440-21-3	0.000000	0	0	
		Magnesium (Mg)	7439-95-4	0.000000	0	0	
		Tin (Sn)	7440-31-5	0.000000	0	0	
			<b>Lead Frame Total:</b>		<b>0.128571</b>	<b>1000000</b>	<b>538721.78</b>
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0	
		Exter. Plating Sn	7440-31-5	0.003749	1000000	15994.0126953	
			<b>External Plating Total:</b>		<b>0.003749</b>	<b>1000000</b>	<b>15994.0126953</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0	
		Inter. Plating Ag	7440-22-4	0.001065	1000000	4287.61669922	
			<b>Internal Plating Total:</b>		<b>0.001065</b>	<b>1000000</b>	<b>4287.61669922</b>
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001471	750000	6275.70605469	
		Tin (Sn)	7440-31-5	0.000000	0	0	
		Lead (Pb)	7439-92-1	0.000000	0	0	
		Silica (SiO2)	60676-86-0	0.000000	0	0	
		Indium (In)	7440-74-6	0.000000	0	0	
		Metal Oxide		0.000000	0	0	
		Antimony (Sb)	7440-36-0	0.000000	0	0	
		Resin (EP)		0.000490	250000	2090.47990847	
			<b>Die Attach Total:</b>		<b>0.001961</b>	<b>1000000</b>	<b>8366.1865244</b>
		Encapsulation	MULTIAROMATIC RESIN BzSb FREE	Resin (EP)		0.009848	103000
Bromine (Br)	40039-09-8			0.000000	0	0	
Silica (SiO2)	60676-86-0			0.085571	895000	365070.3125	
Antimony Trioxide (Sb2O3)	1309-64-4			0.000000	0	0	
Metal Hydroxide				0.000000	0	0	
Carbon Black (C)	1333-86-4			0.000191	2000	814.860534668	
	<b>Encapsulation Total:</b>				<b>0.095610</b>	<b>1000000</b>	<b>407899.5625</b>
Bond Wire Estimated	AFW/TANAKA/Kn	Gold (Au)	7440-57-5	0.000557	1000000	2376.32104492	

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